

Fig. 1

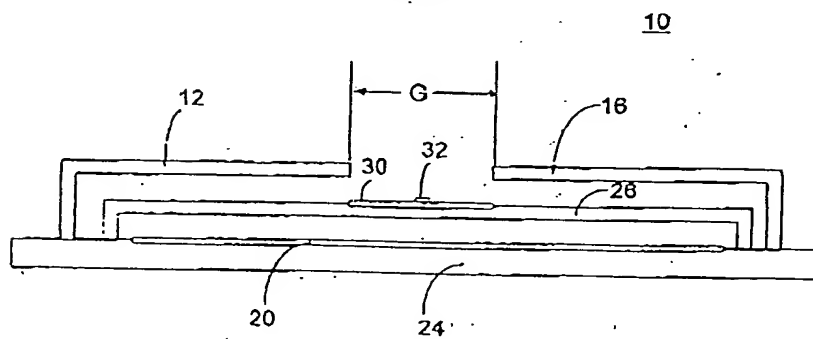


Fig. 2

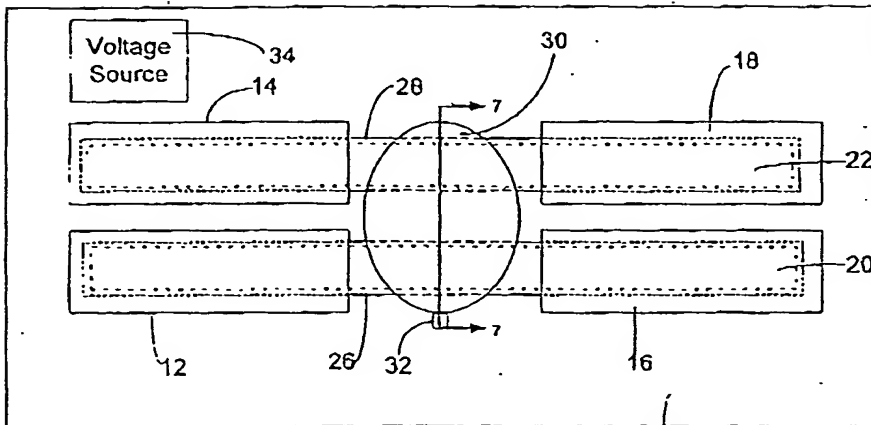


Fig. 3

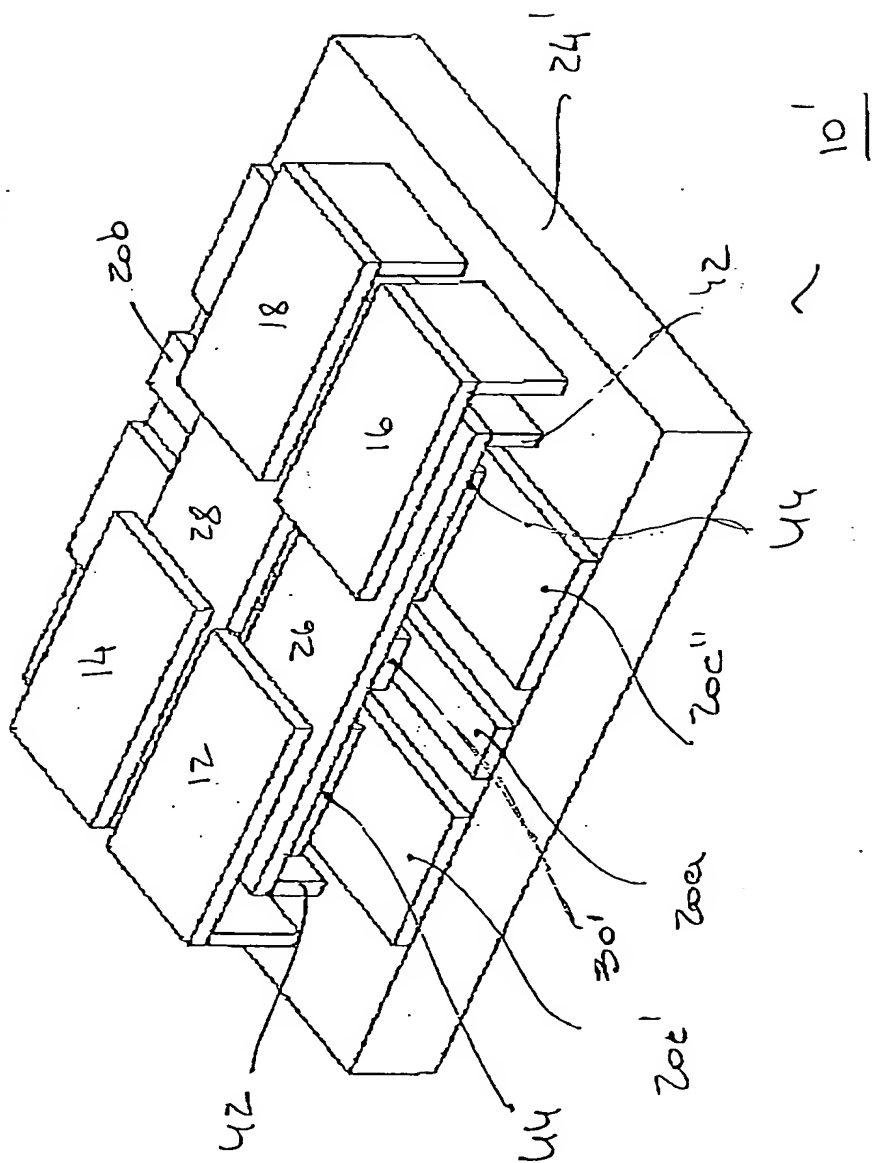


Fig. 5

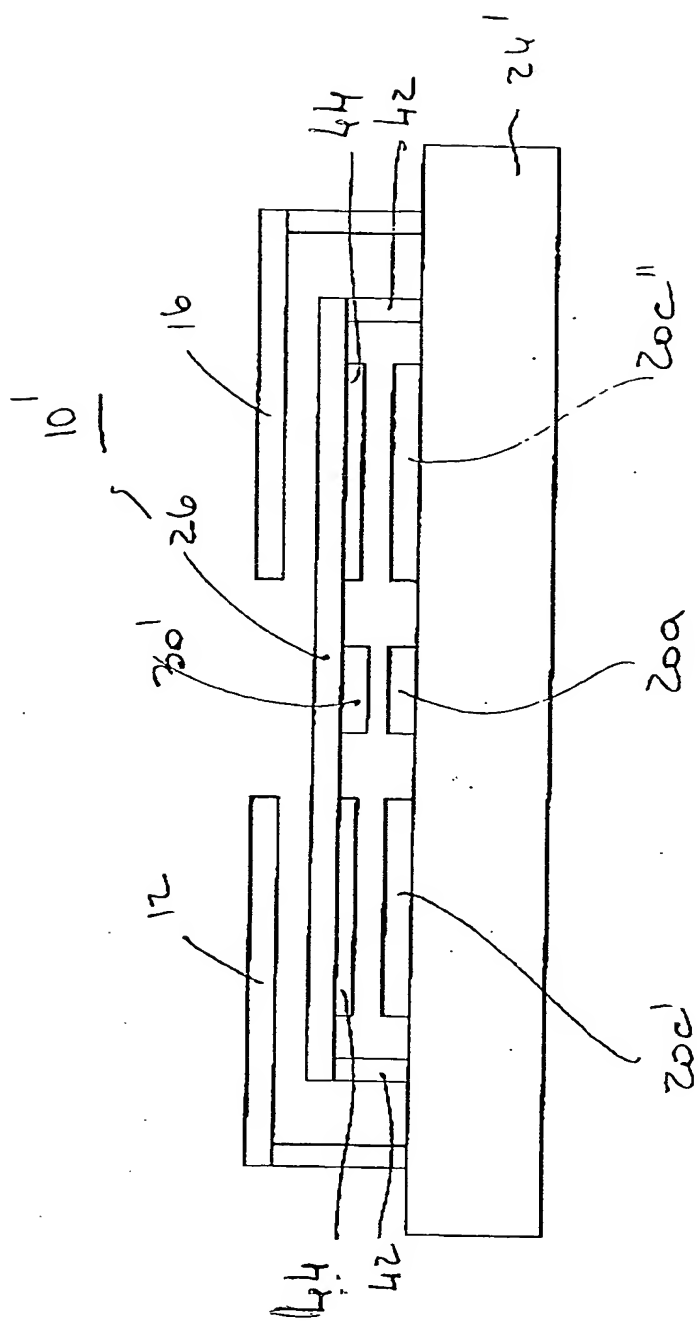


FIG. 5a

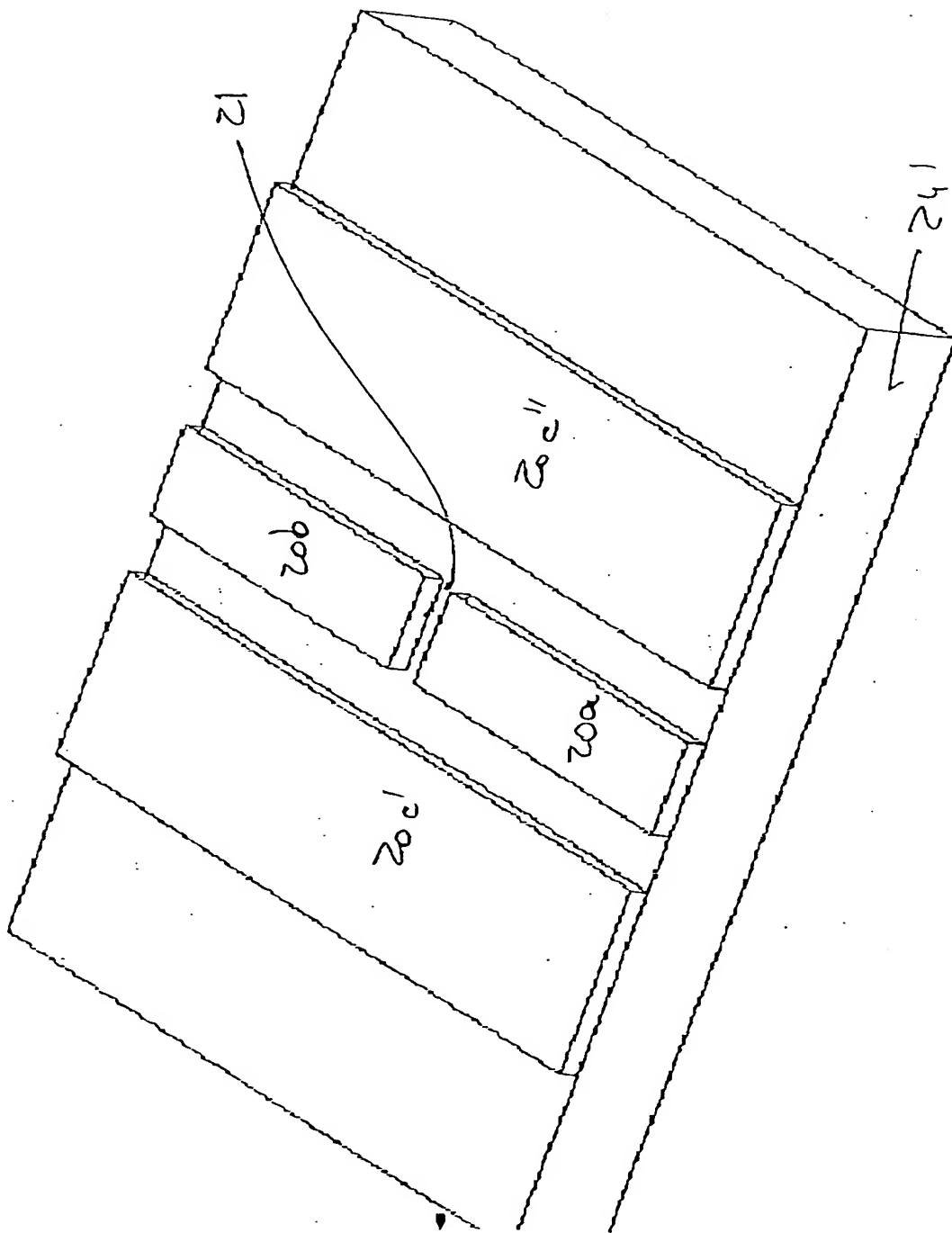


FIG. 5b

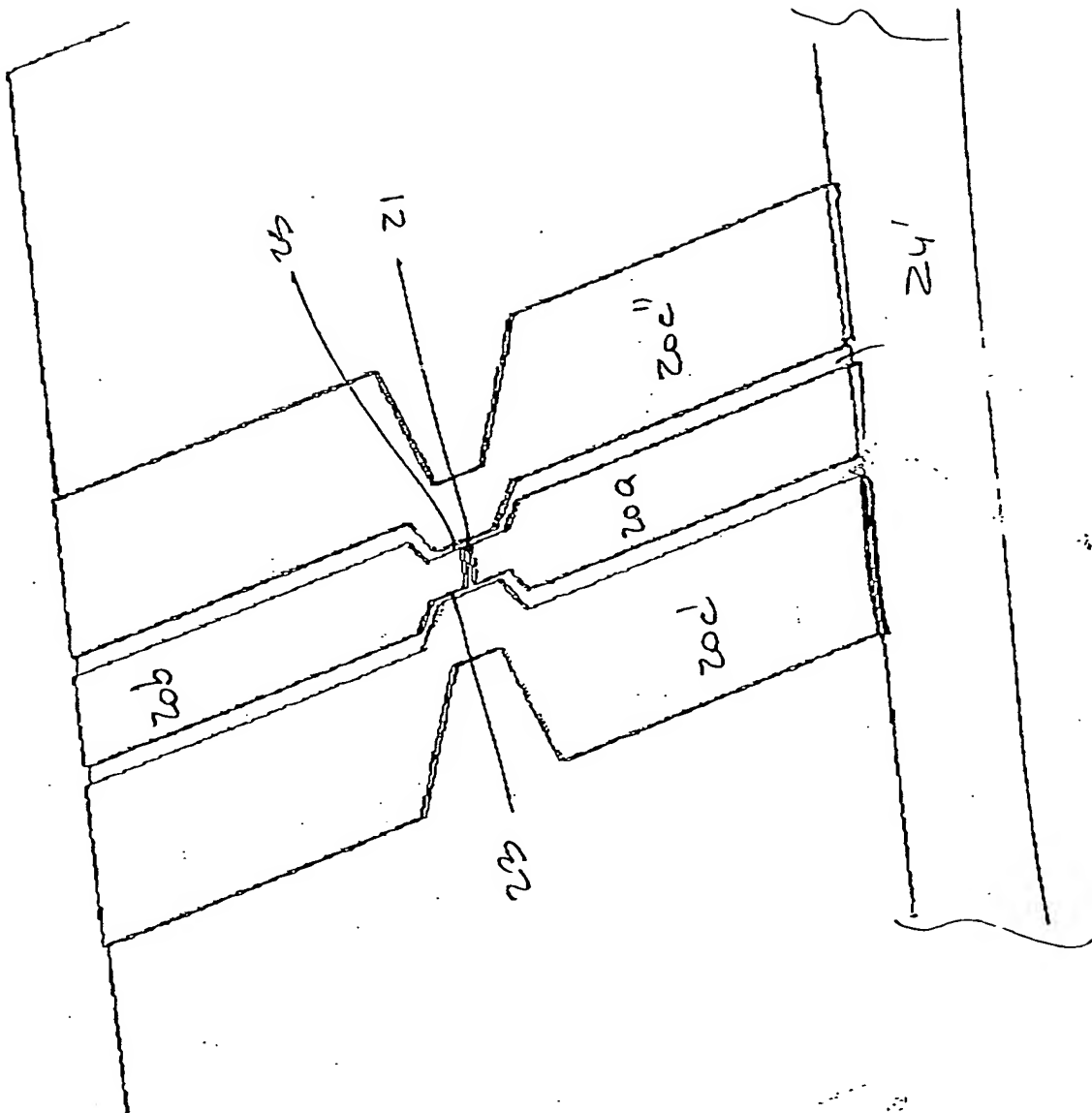


FIG. 5C

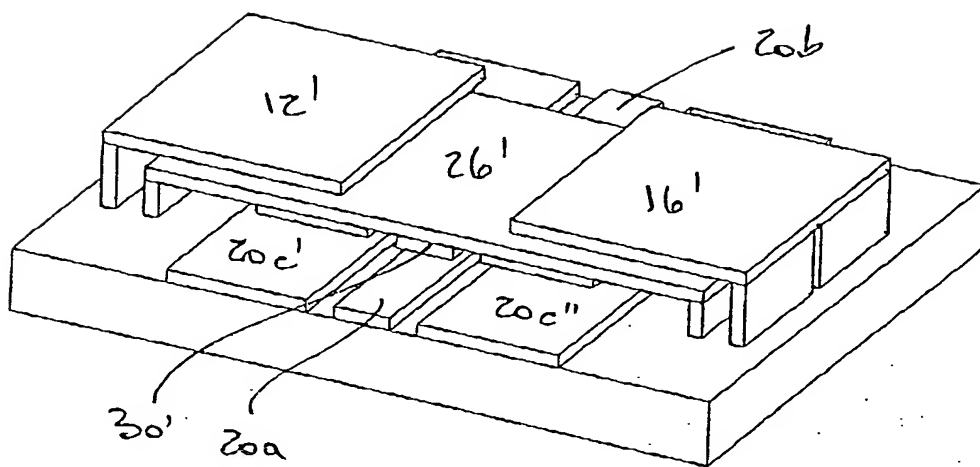


FIG. 6

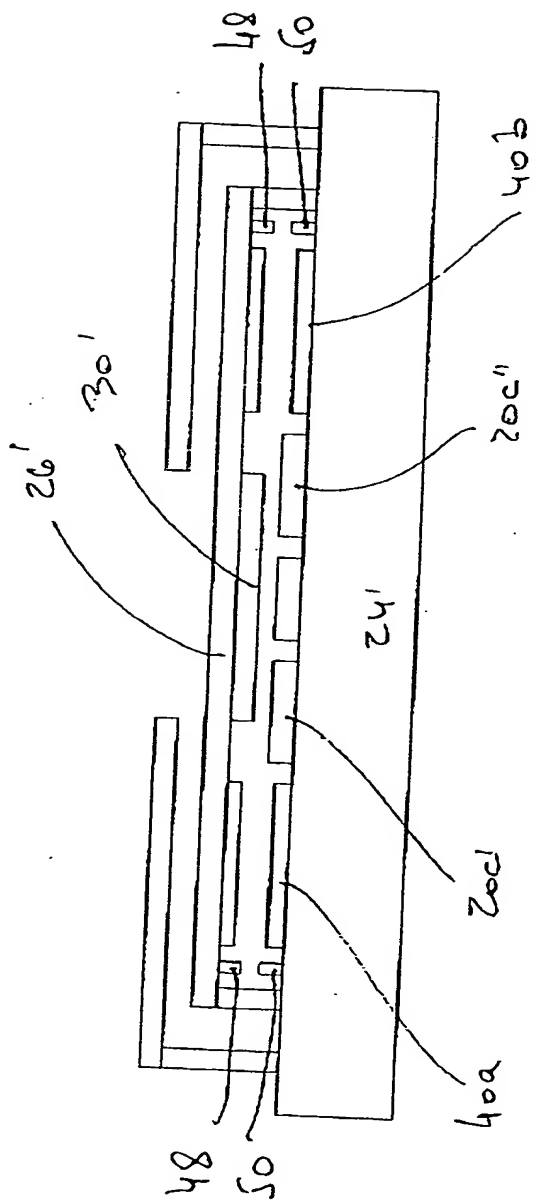
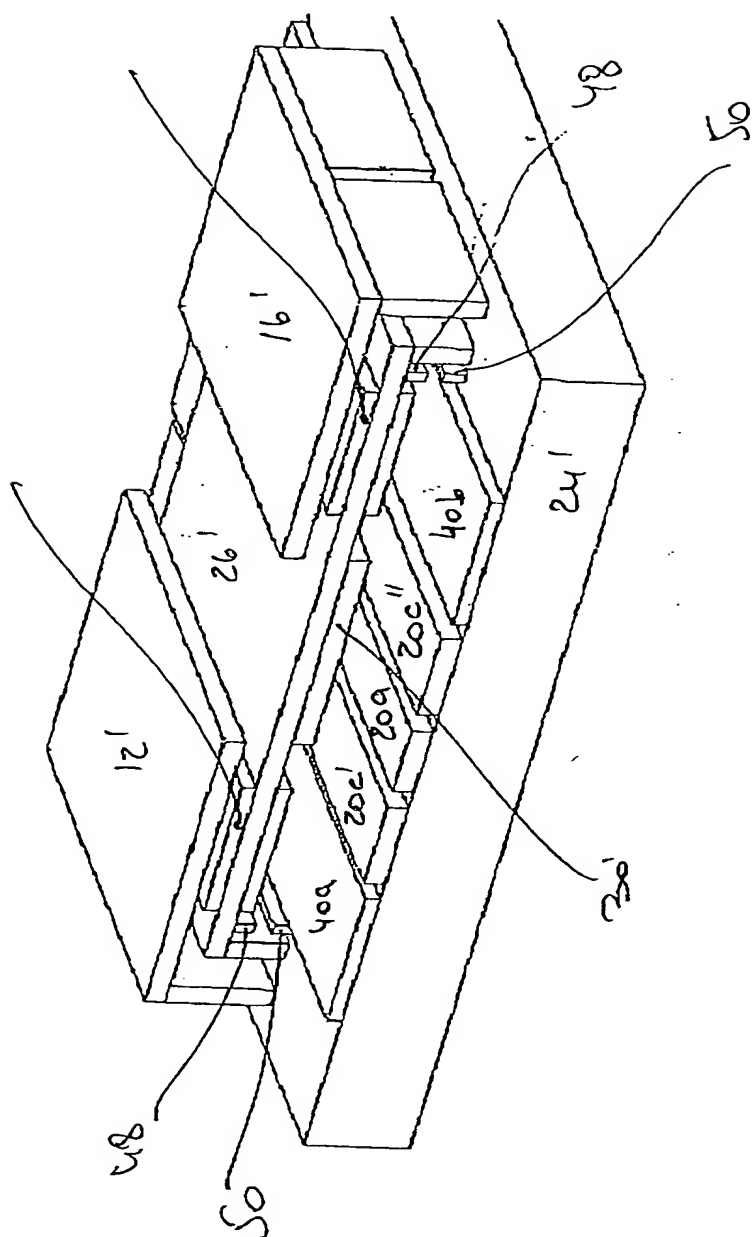


FIG. 7b



8.5.17

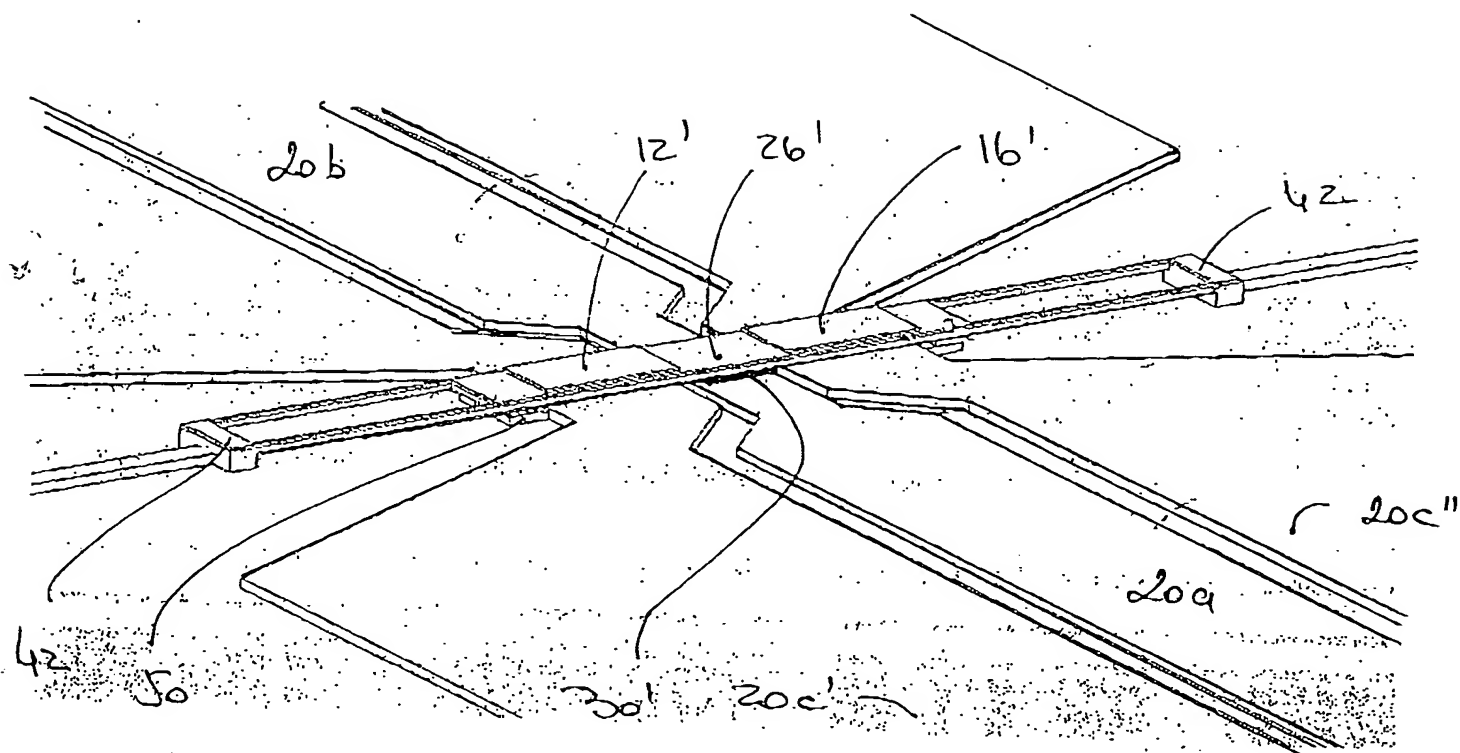


FIG. 9

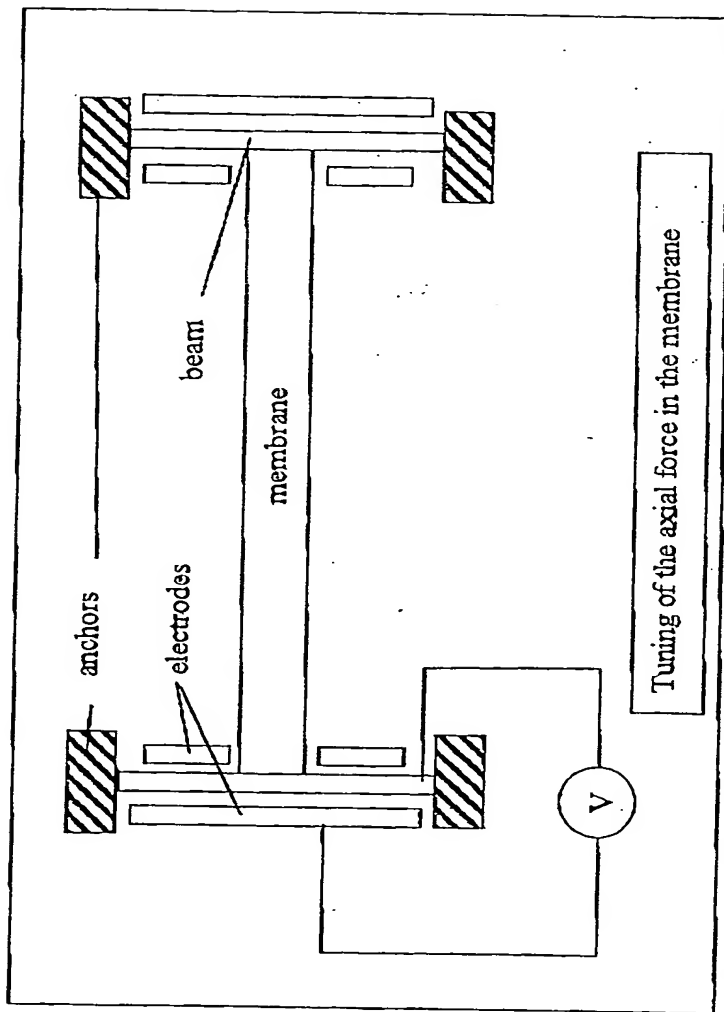


FIG. 10

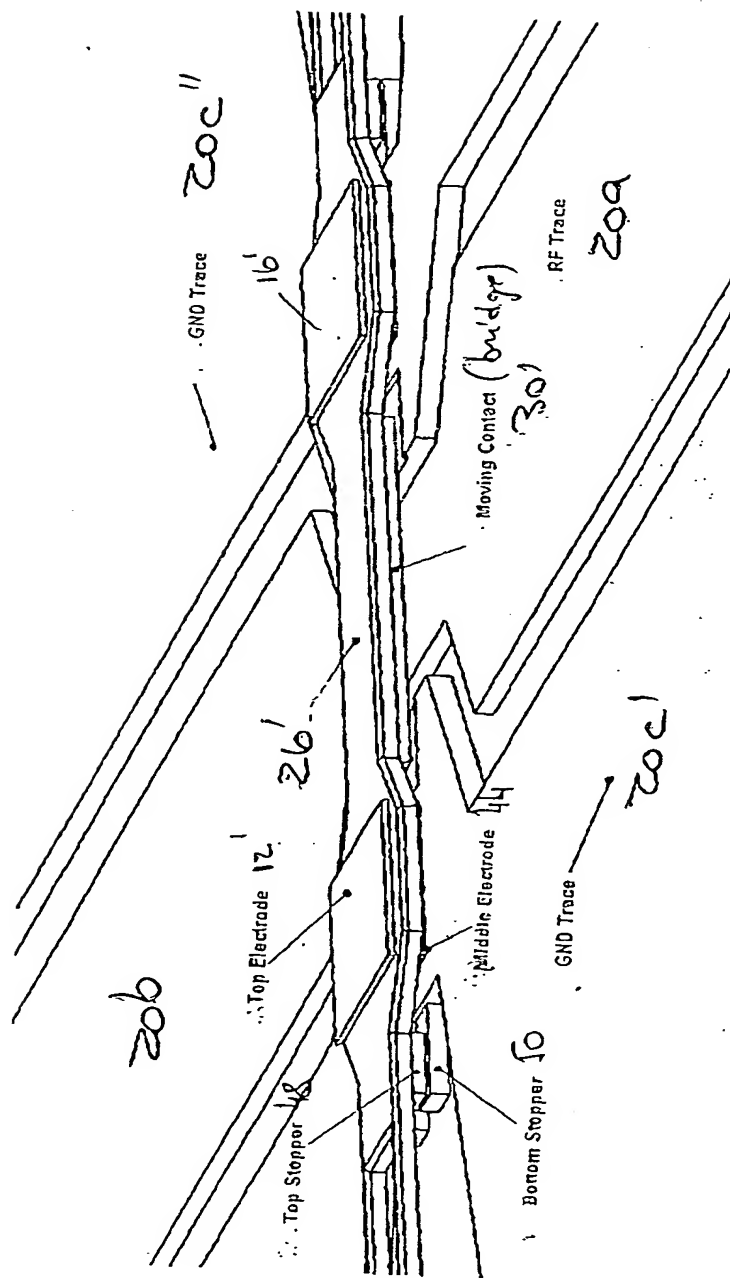


FIG. 11

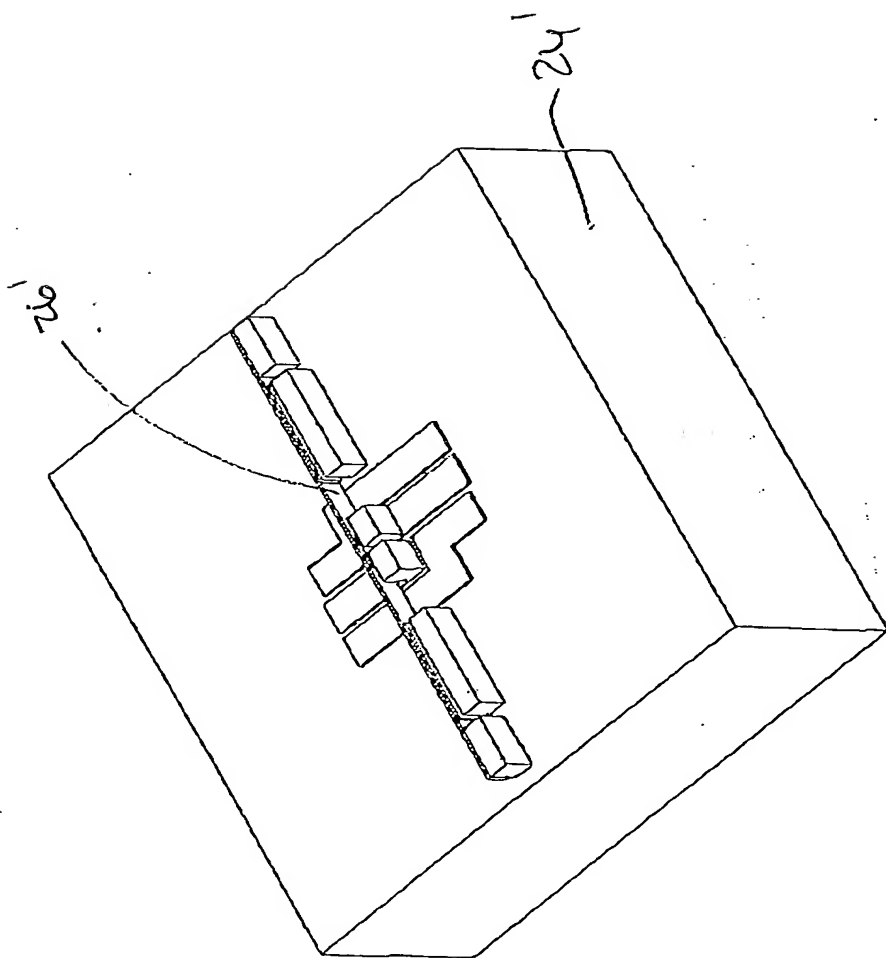


FIG. 12a

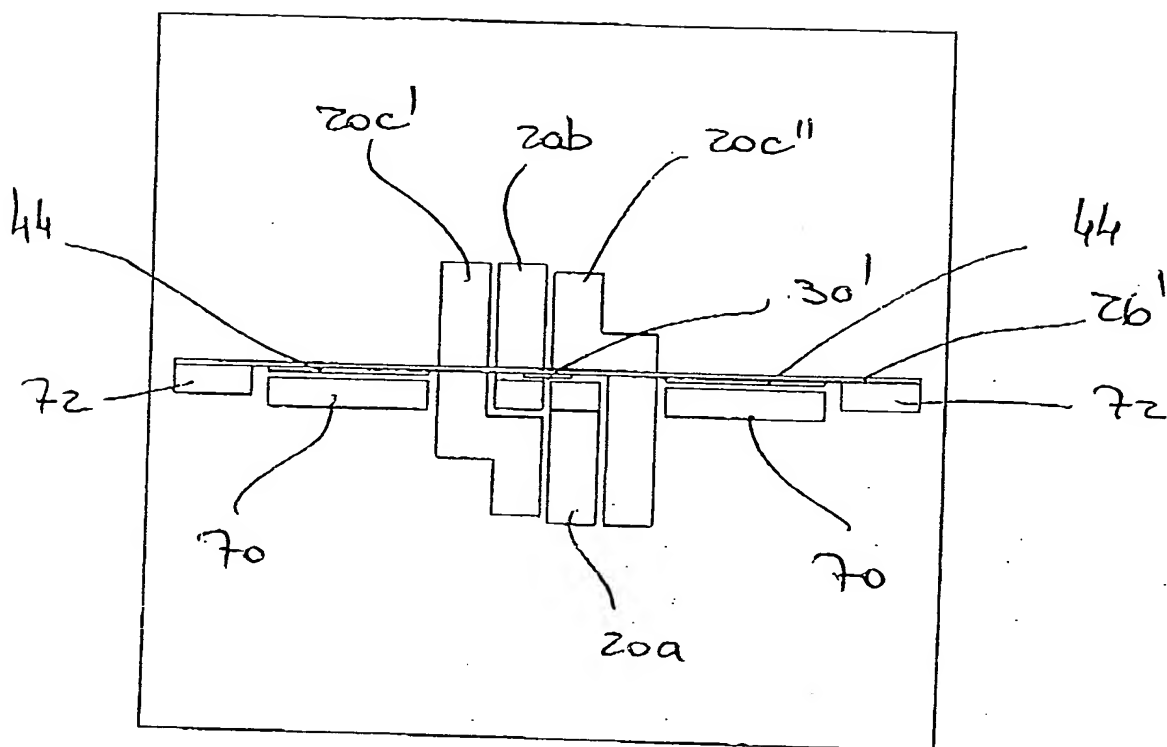
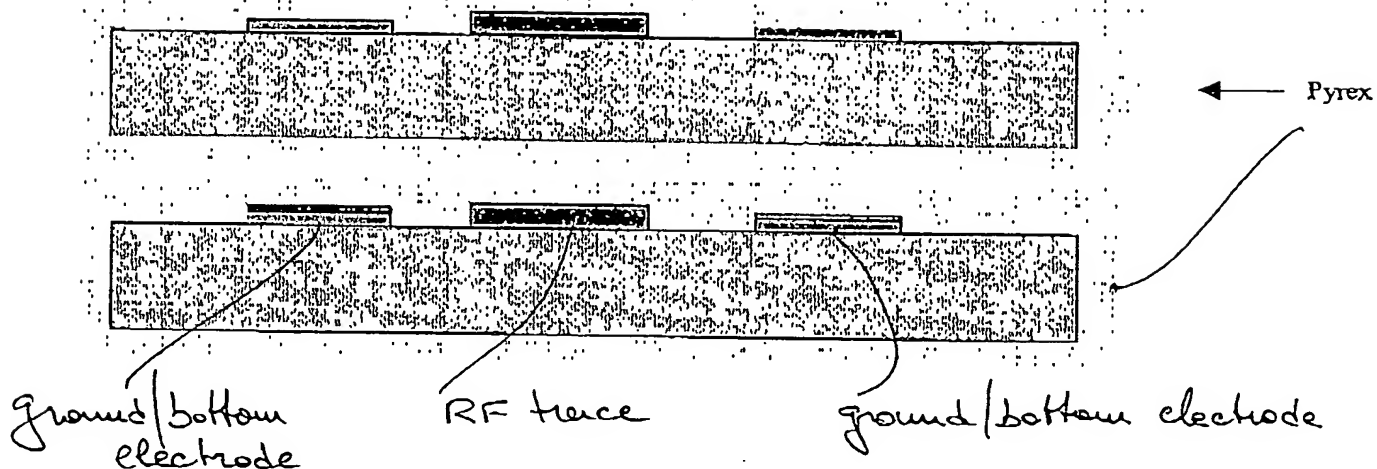


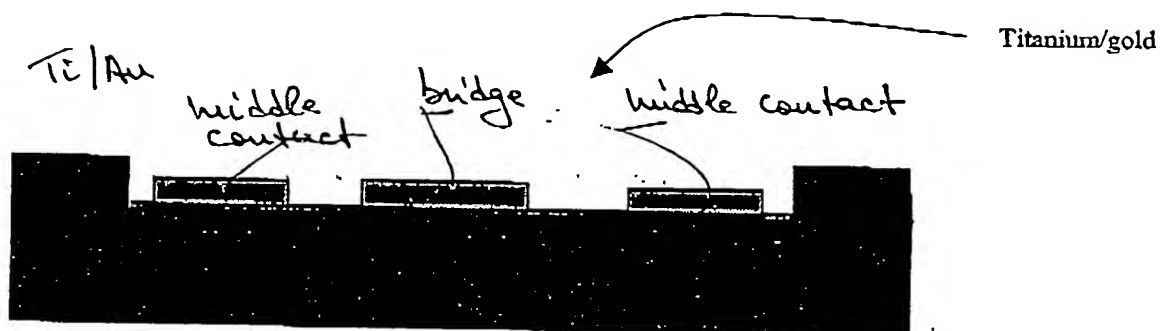
FIG. 12b



a: Wafer 1 Contact line

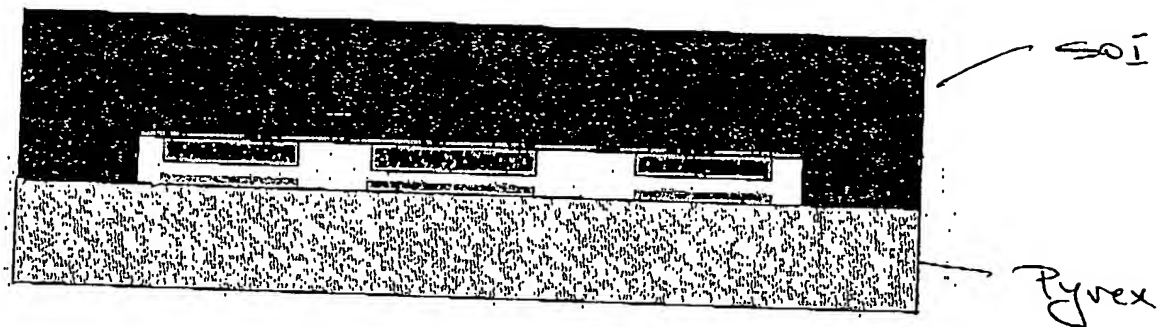


b: Wafer 2 First RIE and Nitride deposition

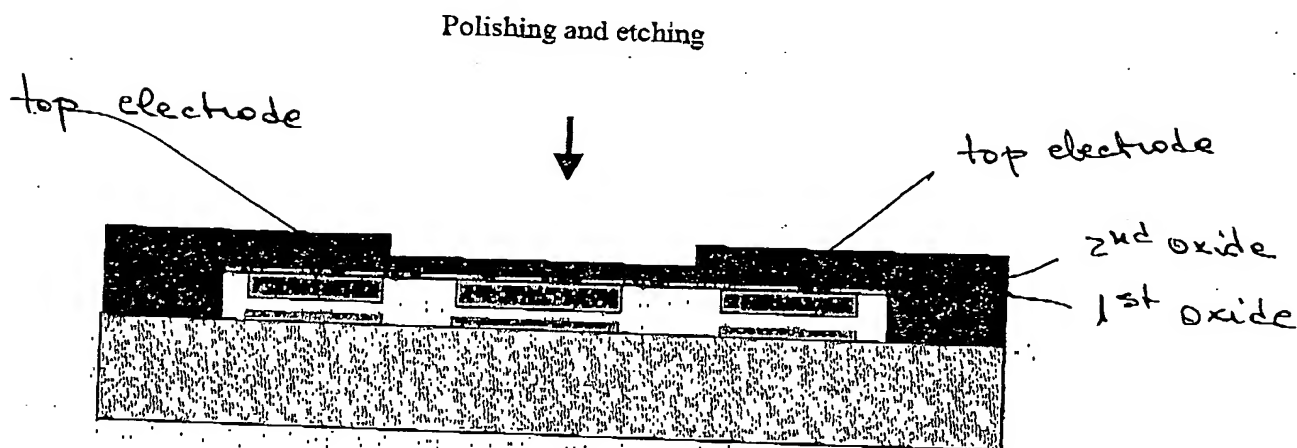


c: Wafer 2 Contact Bridge and Electrodes

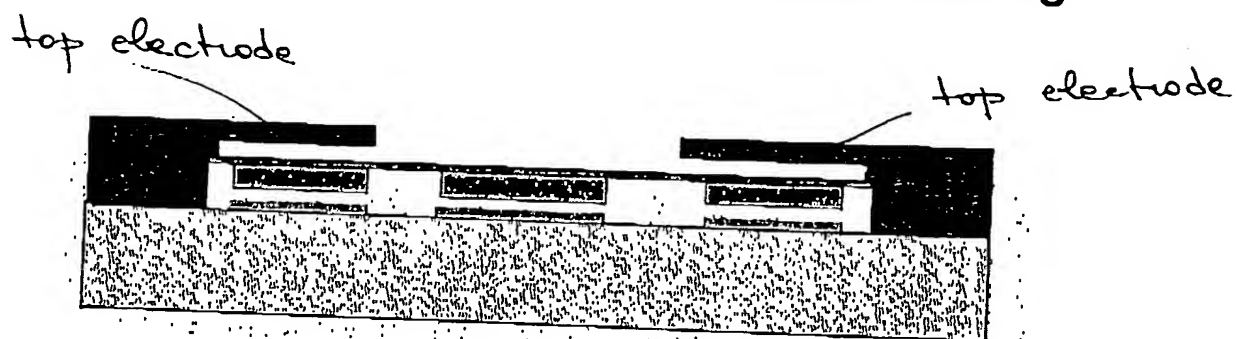
Fig. 13



d: Wafer Bonding



e: Polishing and top electrodes etching



f: Structure R lease

FIG. 13
Continued